# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

## **CONVEYING PARTY DATA**

Name	Execution Date
Kurt H. Junker	09/12/2007
Tien-Ying Luo	09/13/2007
Dina H. Triyoso	09/12/2007

#### **RECEIVING PARTY DATA**

Name:	Freescale Semiconductor, Inc.	
Street Address:	6501 William Cannon Drive West	
Internal Address:	Law Department	
City:	Austin	
State/Country:	TEXAS	
Postal Code:	78735	

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11855557

## **CORRESPONDENCE DATA**

Fax Number: (512)996-6854

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 512-996-6839

Email: pat.thomas@freescale.com

Correspondent Name: Freescale Semiconductor, Inc.

Address Line 1: 7700 West Parmer Lane

Address Line 2: MD: TX32/PL02
Address Line 4: Austin, TEXAS 78729

ATTORNEY DOCKET NUMBER:	MT10696TP
NAME OF SUBMITTER:	Robert L. King

Total Attachments: 8

PATENT REEL: 019829 FRAME: 0766

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PATENT REEL: 019829 FRAME: 0767

#### ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we, KURT H. JUNKER, AUSTIN, TEXAS; TIEN-YING LUO, BEACON, NEW YORK; and, DINA H. TRIYOSO, AUSTIN, TEXAS, have sold, assigned and transferred, and do hereby sell, assign and transfer, unto FREESCALE SEMICONDUCTOR, INC., a corporation of the State of Delaware, having its principal office in Austin, State of Texas, United States of America, and its successors, assigns, and legal representatives, the entire right, title and interest for the United States of America in and to certain inventions relating to improvements in METHOD OF REMOVING DEFECTS FROM A DIELECTRIC MATERIAL IN A SEMICONDUCTOR (Docket No. MT10696TP), described, illustrated and claimed in an application for Letters Patent of the United States of America executed by us on the dates indicated by our signatures below, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation or reissue thereof.

We hereby also sell, assign and transfer unto FREESCALE SEMICONDUCTOR, INC., the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and we further authorize FREESCALE SEMICONDUCTOR, INC. to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation or reissue, to FREESCALE SEMICONDUCTOR, INC., for the sole use and benefit of FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives, to the full end of the term for which Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to FREESCALE SEMICONDUCTOR, INC.

We agree that, when requested, we will, without charge to FREESCALE SEMICONDUCTOR, INC., but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for

the inventions in any and all countries and for vesting title thereto in FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives or nominees.

We covenant with FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

First Witness

NESS DATE: 9/12/2007
(Month-Day-Year)

Second Witness

TIEN-YING LUO	DATE:
<u>First Witness</u>	
SIGNATURE OF WITNESS	DATE:(Month-Day-Year)
PRINTED NAME OF WITNESS	
Second Witness	
SIGNATURE OF WITNESS	DATE:(Month-Day-Year)
PRINTED NAME OF WITNESS	

DINA H. TRIYOSO	DATE:	9/12/2007
First Witness  Refuil halfeyre SIGNATURE OF WITNESS	DATE:	9/12/2007 (Month-Day-Year)
Ritwik Chatterjee PRINTED NAME OF WITNESS		
Second Witness  RML S Jacks  SIGNATURE OF WITNESS	DATE:	9/12/200 7 (Month-Day-Year)
Robert E. Jones PRINTED NAME OF WITNESS		(Month-Day-Year)

# ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we, KURT H. JUNKER, AUSTIN, TEXAS; TIEN-YING LUO, BEACON, NEW YORK; and, DINA H. TRIYOSO, AUSTIN, TEXAS, have sold, assigned and transferred, and do hereby sell, assign and transfer, unto FREESCALE SEMICONDUCTOR, INC., a corporation of the State of Delaware, having its principal office in Austin, State of Texas, United States of America, and its successors, assigns, and legal representatives, the entire right, title and interest for the United States of America in and to certain inventions relating to improvements in METHOD OF REMOVING DEFECTS FROM A DIELECTRIC MATERIAL IN A SEMICONDUCTOR (Docket No. MT10696TP), described, illustrated and claimed in an application for Letters Patent of the United States of America executed by us on the dates indicated by our signatures below, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation or reissuc thereof.

We hereby also sell, assign and transfer unto FREESCALE SEMICONDUCTOR, INC., the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and we further authorize FREESCALE SEMICONDUCTOR, INC. to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation or reissue, to FREESCALE SEMICONDUCTOR, INC., for the sole use and benefit of FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives, to the full end of the term for which Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to FREESCALE SEMICONDUCTOR, INC.

We agree that, when requested, we will, without charge to FREESCALE SEMICONDUCTOR, INC., but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for

the inventions in any and all countries and for vesting title thereto in FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives or nominees.

We covenant with FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

KURT H. JUNKER	DATE:
First Witness	
SIGNATURE OF WITNESS	DATE:(Month-Day-Year)
PRINTED NAME OF WITNESS	
Second Witness	
SIGNATURE OF WITNESS	DATE: (Month-Day-Year)
PRINTED NAME OF WITNESS	

TIEN-YINGLUG	DATE: Sept. 13, 2007
First Witness	,
SIGNATURE OF WITNESS	DATE: Supt 13, 2007 (Month-Day-Year)
PRINTED NAME OF WITNESS	

Second Witness	
Daville. SIGNATURE OF WITNESS	DATE: 09/13/07 (Month-Day-Year)
Daniel Tekleab PRINTED NAME OF WITNESS	

DINA H. TRIYOSO	DATE:
First Witness	
SIGNATURE OF WITNESS	DATE: (Month-Day-Year)
PRINTED NAME OF WITNESS	
Second Witness	
SIGNATURE OF WITNESS	DATE:(Month-Day-Year)
PRINTED NAME OF WITNESS	

MT10696TP

**PATENT** REEL: 019829 FRAME: 0775